



Xinqun Semiconductor (XIAMEN) Inc.  
芯群集成电路(厦门)有限公司

## Supplier Guarantee Letter

Date of writing December (month) 27 (date) 2024 (year)  
Warranty card regarding substances included in products

The undersigned on behalf of **Xinqun Semiconductor (XIAMEN) Inc.**  
At the address of **Room 202, Building NO.34, Guanri Road, Xiamen Software Park II, Xiamen P.R.China**

Our company (that include our subsidiary and associated companies hereafter) hereby Guarantee that all of the Xinqun's products comply with the requirement of 2011/65/EU and 2015/863/EU (RoHS 2.0), the substances are listed as follows.

- 1) Cadmium and cadmium compounds (< 0.01%)
- 2) Lead and lead compounds (we guarantee : plastic part<100ppm ; total<1000ppm)
- 3) Mercury and mercury compounds (< 0.1%)
- 4) Hexavalent chromium compounds (< 0.1%)
- 5) Polybrominated biphenyls (PBB) (< 0.1%)
- 6) Polybrominated diphenylethers (PBDE) (< 0.1%)
- 7) Bis(2-ethylhexyl) phthalate (DEHP) (< 0.1 %)
- 8) Butyl benzyl phthalate (BBP) (< 0.1 %)
- 9) Dibutyl phthalate (DBP) (< 0.1 %)
- 10) Diisobutyl phthalate (DIBP) (< 0.1 %)

Company Name : Xinqun Semiconductor (XIAMEN) Inc.

Organization : Quality Assurance & Reliability Division

Person Responsible : KEN WU

Person in Charge: RICH LAI